

## IN THE CLAIMS

Please amend the claims as follows:

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1. (Currently Amended) A method of manufacturing a component of a droplet deposition apparatus, the component comprising a body and a base, the body comprising piezoelectric material having a plurality of channels each with a channel surface, the body being attached to a surface of the base which is free of substantial discontinuities; the method comprising the steps of attaching the body to said surface of the base; and depositing a layer of conductive material so as to extend continuously over said surface of the base and at least one of said channel surfaces to provide an electrode on each channel surface and a conductive track on said surface of the base, the conductive track being ~~which is~~ integrally connected to the electrode.

2. (Previously Amended) A method according to Claim 1, comprising the further step of removing regions of the layer of conductive material to define electrodes for different channels, which electrodes are electrically isolated one from another.

3. (Previously Amended) A method according to Claim 1, comprising the further step of removing regions of the layer of conductive material to define conductive tracks which are electrically isolated one from another.

4. (Previously Amended) A method according to Claim 3, comprising the step of removing said regions of the layer of conductive material through local vaporization of conductive material.

5. (Previously Amended) A method according to Claim 4, comprising the step of vaporizing said conductive material through the use of a laser beam.

6. (Previously Amended) A method according to Claim 2, wherein a land is defined between neighboring channels on the body and the method comprising the step of removing a strip of conductive material from the land.

7. (Previously Amended) A method according to Claim 1, comprising the step of depositing said layer in a pattern to define electrodes for different channels, which electrodes are electrically isolated one from another.

8. (Previously Amended) A method according to Claim 1, comprising the step of depositing said layer in a pattern defining a plurality of said conductive tracks which are electrically isolated one from another.

9. (Previously Amended) A method according to Claim 7, comprising the step of achieving patterning of the deposited conductive layer through the use of masking.

10. (Previously Amended) A method according to Claim 1, comprising the step of attaching the body to the base prior to formulation of the channels in the body.

11. (Previously Amended) A method according to Claim 10, comprising the step of forming the channels by removing regions of the body.

12. (Previously Amended) A method according to Claim 11, wherein the step of removing regions of the body defines discrete walls of piezoelectric material, separated one from each other.

13. (Previously Amended) A method according to Claim 11, wherein the step of removing regions of the body also removes regions of the base.

14. (Previously Amended) A method according to Claim 1, comprising the step of chamfering the body adjacent the base to provide regions of the deposited layer of conductive material which overlies the body and the base respectively and which meet at an obtuse angle.

15. (Previously Amended) A method according to Claim 1, comprising the step of attaching the body to the base through adhesive, there being defined between the body and the base a fillet of said adhesive which serves as a key for the deposited layer of conductive material.

16-22. (Canceled)

23. (Previously Added) A method according to Claim 2, comprising the further step of removing regions of the layer of conductive material to define conductive tracks which are electrically isolated one from another.

24. (Previously Amended) A method according to Claim 23, comprising the step of removing said regions of the layer of conductive material through local vaporization of conductive material.

25. (Previously Amended) A method according to Claim 24, comprising the step of vaporizing said conductive material through the use of a laser beam.

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